



Title of Change:	SOIC-8 Insourcing to ON Semiconductor Philippines (OSPI) Factory from HANA (Thailand) – Phase 2										
Proposed first ship date:	22 August 2018										
Contact information:	Contact your local ON Semiconductor Sales Office or <Scott.Brow@onsemi.com>										
Samples:	Contact your local ON Semiconductor Sales Office										
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Kyungwon.Kang@onsemi.com>.										
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.										
Change Part Identification:	Product marked with date code 1820 or later may be built from current factory or from OSPI Factory. The trace code marking on Line 2 is of the form ALYW where A = Assembly Location, L = Wafer Lot ID and YW is a 2-digit date code. Product marked with "P" as the assembly location will be from OSPI. Additionally on the label of the box and reel, the ASSY LOC: PO will also indicate product assembled in OSPI. Please see sample label on Page 2 at the following URL http://www.onsemi.com/pub/Collateral/LABELRM-D.PDF to see the location of the ASSY LOC.										
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____										
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____										
Sites Affected:	ON Semiconductor Sites: ON Carmona, Philippines	External Foundry/Subcon Sites: HANA, Thailand									
Description and Purpose:											
<p>ON Semiconductor would like to inform its customers of the qualification of ON Semiconductor Philippines (OSPI) for the assembly and test of all of the SOIC-8 products listed in this Final Product Change Notification (FPCN). This is a capacity expansion, and at the end of the FPCN approval cycle, these products may be dual sourced from either HANA, Thailand or from OSPI.</p> <p>For Test, consigned testers and handlers as HANA have been transferred to OSPI to support the testing of products. The same load boards, test programs and other necessary hardware used in HANA, will be used to test the products listed.</p> <p>For assembly, BOM changes associated with this FPCN are shown here:</p>											
	<table border="1"> <thead> <tr> <th>Material to be changed</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>Hitachi CEL8240HF10LYR</td> <td>Sumitomo G600</td> </tr> <tr> <td>Die Attach</td> <td>Henkel QMI 519</td> <td>Henkel ABP-8062T</td> </tr> </tbody> </table>		Material to be changed	Before Change Description	After Change Description	Mold Compound	Hitachi CEL8240HF10LYR	Sumitomo G600	Die Attach	Henkel QMI 519	Henkel ABP-8062T
Material to be changed	Before Change Description	After Change Description									
Mold Compound	Hitachi CEL8240HF10LYR	Sumitomo G600									
Die Attach	Henkel QMI 519	Henkel ABP-8062T									



Additionally, this FPCN serves to notify customers of a change in the marking for all products listed for **BOTH** sites, HANA and OSPI. The new marking will be of the form:



Line 1 is the Product Identification (see table for new Product IDs)

Line 2 is the Trace code with the following nomenclature: A = Assy Location, L = Wafer Lot ID, YW = 2 digit date code. The X at the end of the line is a wrap character if additional identification is needed from Line 1.

HANA: A = H

OSPI: A = P

OPN	Line 1 Marking
FAN7930BMX	7930B
FAN7930BMX-G	7930B
FAN7930CMX	7930C

OPN	Line 1 Marking
FAN7930CMX-G	7930C
FL7930BMX-G	FL7930B
FL7930CMX-G	FL7930C

Reliability Data Summary:

QV DEVICE NAME FAN7930BMX

RMS K46691, O47069

PACKAGE SOIC 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 80 % max rated <u>Vcc</u>	1008 hrs	0/80
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/77
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/80
THB	JESD22-A101C	85°C, 85% RH, bias	504 hrs	0/80
<u>uHAST</u>	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/80
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	-	0/320
SAT	JEDEC STD 035	Pre and Post MSL 1	-	0/25
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30
SD	JSTD002	Ta = 245C, 10 sec	-	0/15
PD	JESD22-B100	Per POD, case 751EB	-	0/30

Electrical Characteristic Summary:

Electrical characteristics are not impacted by this change. Electrical comparison reports are available upon request



List of Affected Standard Parts:

Part Number	Qualification Vehicle
FAN7930BMX	FAN7930BMX
FAN7930BMX-G	
FAN7930CMX	
FAN7930CMX-G	
FL7930BMX-G	
FL7930CMX-G	



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
FAN7930BMX		FAN7930BMX
FAN7930BMX-G		FAN7930BMX
FAN7930CMX		FAN7930BMX
FAN7930CMX-G		FAN7930BMX
FL7930BMX-G		FAN7930BMX
FL7930CMX-G		FAN7930BMX